June 1998

National Semiconductor

DS90C031 LVDS Quad CMOS Differential Line Driver

General Description

The DS90C031 is a quad CMOS differential line driver designed for applications requiring ultra low power dissipation and high data rates. The device is designed to support data rates in excess of 155.5 Mbps (77.7 MHz) utilizing Low Voltage Differential Signaling (LVDS) technology.

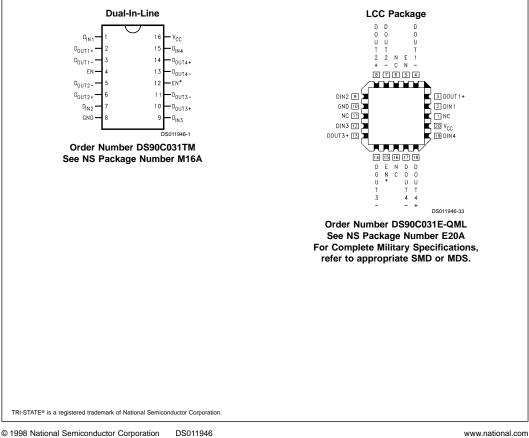
The DS90C031 accepts TTL/CMOS input levels and translates them to low voltage (350 mV) differential output signals. In addition the driver supports a TRI-STATE[®] function that may be used to disable the output stage, disabling the load current, and thus dropping the device to an ultra low idle power state of 11 mW typical.

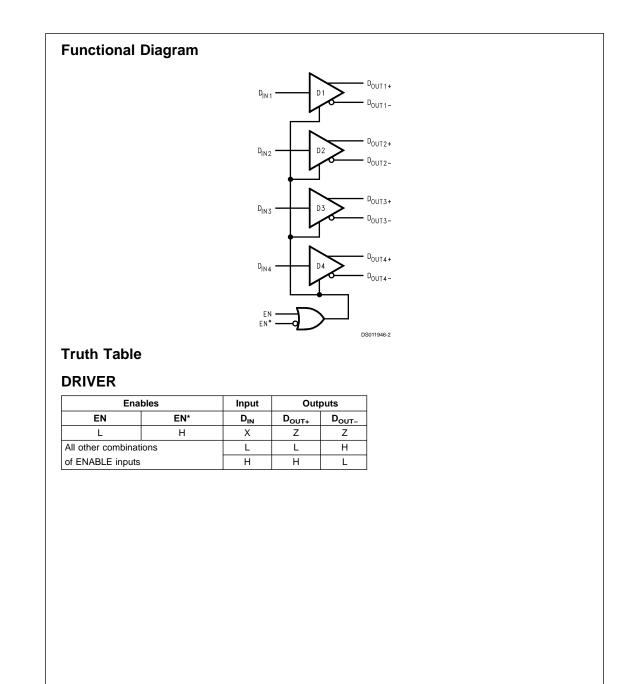
The DS90C031 and companion line receiver (DS90C032) provide a new alternative to high power psuedo-ECL devices for high speed point-to-point interface applications.

Features

- >155.5 Mbps (77.7 MHz) switching rates
- ±350 mV differential signaling
- Ultra low power dissipation
- 400 ps maximum differential skew (5V, 25°C)
- 3.5 ns maximum propagation delay
- Industrial operating temperature range
- Military operating temperature range option
- Available in surface mount packaging (SOIC) and (LCC)
 Pin compatible with DS26C31, MB571 (PECL) and
- 41LG (PECL)
- Compatible with IEEE 1596.3 SCI LVDS standard
- Conforms to ANSI/TIA/EIA-644 LVDS standard
- Available to Standard Microcircuit Drawing (SMD) 5962-95833

Connection Diagrams





.

Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Supply Voltage (V _{CC})	-0.3V to +6V
Input Voltage (D _{IN})	-0.3V to (V _{CC} + 0.3V)
Enable Input Voltage (EN, EN*)	–0.3V to (V _{CC} + 0.3V)
Output Voltage (D _{OUT+} , D _{OUT-})	–0.3V to (V _{CC} + 0.3V)
Short Circuit Duration	
(D _{OUT+} , D _{OUT-})	Continuous
Maximum Package Power Dissip	pation @ +25°C
M Package	1068 mW
E Package	1900 mW
Derate M Package	8.5 mW/°C above +25°C
Derate E Package	12.8 mW/°C above +25°C
Storage Temperature Range	–65°C to +150°C
Lead Temperature Range Soldering (4 sec.)	+260°C

Maximum Junction Temperature (DS90C031T)	+150°C
Maximum Junction Temperature (DS90C031E)	+175°C
ESD Rating (Note 7)	
(HBM, 1.5 kΩ, 100 pF)	≥ 3,500V
(EIAJ, 0 Ω, 200 pF)	≥ 250V

Recommended Operating Conditions

	Min	Тур	Max	Units
Supply Voltage (V _{CC})	+4.5	+5.0	+5.5	V
Operating Free Air Tempe	erature (T	م)		
DS90C031T	-40	+25	+85	°C
DS90C031E	-55	+25	+125	°C

Electrical Characteristics

Symbol	Parameter	Conditions		Pin	Min	Тур	Max	Units
V _{OD1}	Differential Output Voltage	$R_{L} = 100\Omega \ (Figure \ 1)$		D _{OUT-} ,	250	345	450	mV
ΔV_{OD1}	Change in Magnitude of V _{OD1} for Complementary Output States					4	35	mV
Vos	Offset Voltage				1.125	1.25	1.375	V
ΔV _{OS}	Change in Magnitude of $V_{\rm OS}$ for Complementary Output States					5	25	mV
V _{OH}	Output Voltage High	$R_{L} = 100\Omega$				1.41	1.60	V
V _{OL}	Output Voltage Low				0.90	1.07		V
VIH	Input Voltage High			D _{IN} ,	2.0		V _{cc}	V
VIL	Input Voltage Low			EN,	GND		0.8	V
I _I	Input Current	$V_{IN} = V_{CC}, \text{ GND}, 2.5 \text{V or } 0.$	4V	EN*	-10	±1	+10	μA
V _{CL}	Input Clamp Voltage	I _{CL} = -18 mA]	-1.5	-0.8		V
l _{os}	Output Short Circuit Current	V _{OUT} = 0V (Note 8)		D _{OUT-} ,		-3.5	-5.0	mA
I _{oz}	Output TRI-STATE Current	EN = 0.8V and EN* = 2.0V, V _{OUT} = 0V or V _{CC}		D _{OUT+}	-10	±1	+10	μA
I _{cc}	No Load Supply Current	$D_{IN} = V_{CC}$ or GND	DS90C031T	V _{cc}		1.7	3.0	mA
	Drivers Enabled	D _{IN} = 2.5V or 0.4V]			4.0	6.5	mA
I _{CCL}	Loaded Supply Current Drivers Enabled	$R_L = 100\Omega$ All Channels $V_{IN} = V_{CC}$ or GND	DS90C031T			15.4	21.0	mA
		(all inputs)	DS90C031E			15.4	25.0	mA
I _{ccz}	No Load Supply Current	$D_{IN} = V_{CC}$ or GND	DS90C031T			2.2	4.0	mA
	Drivers Disabled	$EN = GND, EN^* = V_{CC}$	DS90C031E			2.2	10.0	mA

Over supply voltage and operating temperature ranges, unless otherwise specified. (Notes 2, 3)

Switching Characteristics

$V_{CC} = +5.0V, T_{A}$	= +25°C DS90C031T.	(Notes 3,	4, 6	5, 9)

Symbol	Parameter	Conditions	Min	Тур	Max	Units
t _{PHLD}	Differential Propagation Delay High to Low	$R_{L} = 100\Omega, C_{L} = 5 \text{ pF}$	1.0	2.0	3.0	ns
t _{PLHD}	Differential Propagation Delay Low to High	(Figure 2 and Figure 3)	1.0	2.1	3.0	ns
t _{SKD}	Differential Skew t _{PHLD} - t _{PLHD}		0	80	400	ps
t _{SK1}	Channel-to-Channel Skew (Note 4)		0	300	600	ps

Switching Characteristics (Continued)

•

V _{CC} = +5.0V, T _A = +25°C DS90C031T	(Notes 3, 4, 6, 9)
V _{CC} = 10.0V, 1 _A = 120 0 00000011	(1,0,0,0,0,0,0)

Symbol	Parameter	Conditions	Min	Тур	Max	Units
t _{TLH}	Rise Time			0.35	1.5	ns
t _{THL}	Fall Time			0.35	1.5	ns
t _{PHZ}	Disable Time High to Z	$R_L = 100\Omega,$ $C_L = 5 pF$		2.5	10	ns
t _{PLZ}	Disable Time Low to Z			2.5	10	ns
t _{PZH}	Enable Time Z to High	(Figure 4 and Figure 5)		2.5	10	ns
t _{PZL}	Enable Time Z to Low			2.5	10	ns

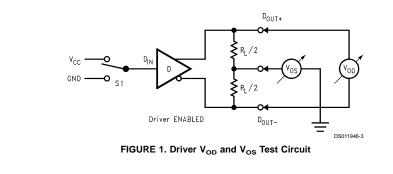
Switching Characteristics V_{CC} = +5.0V ± 10%, T_A = -40°C to +85°C DS90C031T. (Notes 3, 4, 5, 6, 9)

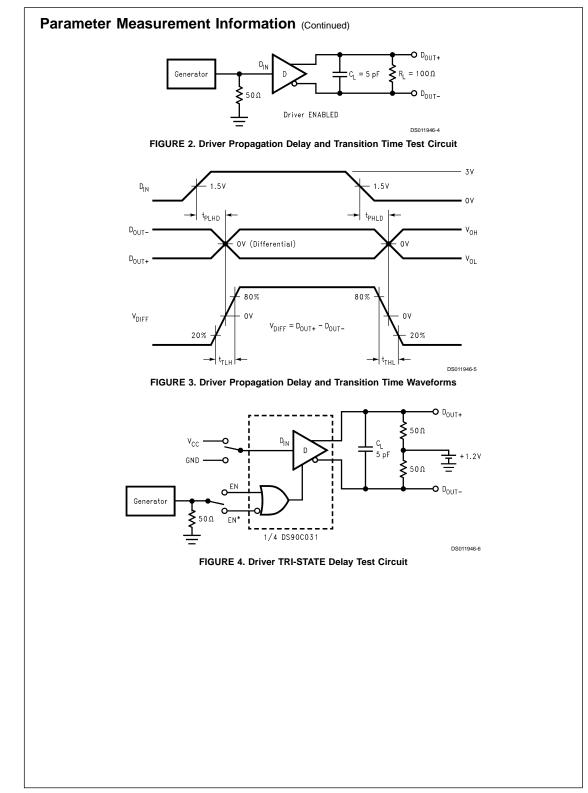
Symbol	Parameter	Conditions	Min	Тур	Max	Units
t _{PHLD}	Differential Propagation Delay High to Low	$R_{L} = 100\Omega, C_{L} = 5 \text{ pF}$	0.5	2.0	3.5	ns
t _{PLHD}	Differential Propagation Delay Low to High	(Figure 2 and Figure 3)	0.5	2.1	3.5	ns
t _{SKD}	Differential Skew t _{PHLD} - t _{PLHD}		0	80	900	ps
t _{SK1}	Channel-to-Channel Skew (Note 4)		0	0.3	1.0	ns
t _{SK2}	Chip to Chip Skew (Note 5)				3.0	ns
t _{TLH}	Rise Time			0.35	2.0	ns
t _{THL}	Fall Time			0.35	2.0	ns
t _{PHZ}	Disable Time High to Z	R _L = 100Ω,		2.5	15	ns
t _{PLZ}	Disable Time Low to Z	C _L = 5 pF		2.5	15	ns
t _{PZH}	Enable Time Z to High	(Figure 4 and Figure 5)		2.5	15	ns
t _{PZL}	Enable Time Z to Low			2.5	15	ns

Switching Characteristics V_{CC} = +5.0V ± 10%, T_A = -55°C to +125°C DS90C031E. (Notes 3, 4, 5, 6, 9, 10)

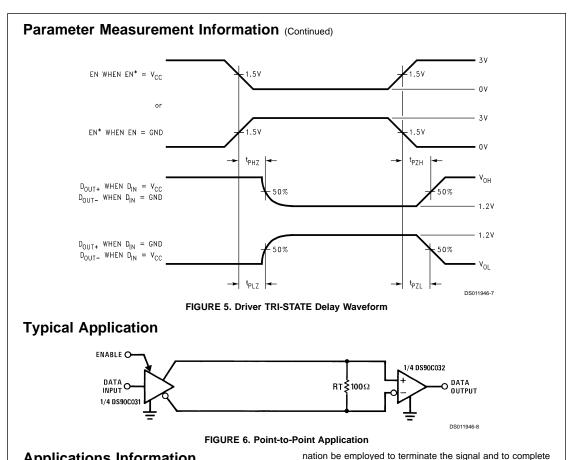
Symbol	Parameter	Conditions	Min	Тур	Max	Units
t _{PHLD}	Differential Propagation Delay High to Low	$R_{L} = 100\Omega, C_{L} = 20 \text{ pF}$	0.5	2.0	5.0	ns
t _{PLHD}	Differential Propagation Delay Low to High	(Figure 3)	0.5	2.1	5.0	ns
t _{SKD}	Differential Skew t _{PHLD} - t _{PLHD}	C _L Connected between	0	0.08	3.0	ns
t _{SK1}	Channel-to-Channel Skew (Note 4)	each Output and GND	0	0.3	3.0	ns
t _{SK2}	Chip to Chip Skew (Note 5)				4.5	ns
t _{PHZ}	Disable Time High to Z	$R_{L} = 100\Omega,$		2.5	20	ns
t _{PLZ}	Disable Time Low to Z	C _L = 5 pF		2.5	20	ns
t _{PZH}	Enable Time Z to High	(Figure 4 and Figure 5)		2.5	20	ns
t _{PZL}	Enable Time Z to Low			2.5	20	ns

Parameter Measurement Information





5



Applications Information

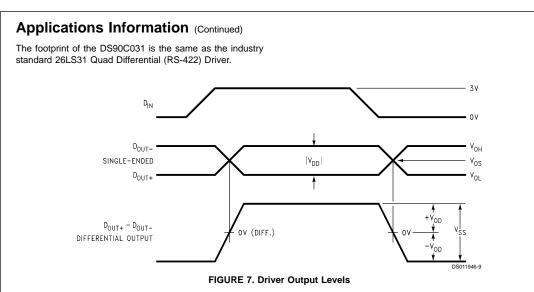
LVDS drivers and receivers are intended to be primarily used in an uncomplicated point-to-point configuration as is shown in Figure 6. This configuration provides a clean signaling environment for the quick edge rates of the drivers. The receiver is connected to the driver through a balanced media which may be a standard twisted pair cable, a parallel pair cable, or simply PCB traces. Typically, the characteristic impedance of the media is in the range of 100Ω . A termination resistor of 100Ω should be selected to match the media, and is located as close to the receiver input pins as possible. The termination resistor converts the current sourced by the driver into a voltage that is detected by the receiver. Other configurations are possible such as a multi-receiver configuration, but the effects of a mid-stream connector(s), cable stub(s), and other impedance discontinuities as well as ground shifting, noise margin limits, and total termination loading must be taken into account.

The DS90C031 differential line driver is a balanced current source design. A current mode driver, generally speaking has a high output impedance and supplies a constant current for a range of loads (a voltage mode driver on the other hand supplies a constant voltage for a range of loads). Current is switched through the load in one direction to produce a logic state and in the other direction to produce the other logic state. The typical output current is mere 3.4 mA, a minimum of 2.5 mA, and a maximum of 4.5 mA. The current mode requires (as discussed above) that a resistive termi-

www.national.com

the loop as shown in Figure 6. AC or unterminated configurations are not allowed. The 3.4 mA loop current will develop a differential voltage of 340 mV across the 100Ω termination resistor which the receiver detects with a 240 mV minimum differential noise margin neglecting resistive line losses (driven signal minus receiver threshold (340 mV - 100 mV = 240 mV)). The signal is centered around +1.2V (Driver Offset, V_{OS}) with respect to ground as shown in Figure 7. Note that the steady-state voltage (V_{SS}) peak-to-peak swing is twice the differential voltage (V_{OD}) and is typically 680 mV. The current mode driver provides substantial benefits over voltage mode drivers, such as an RS-422 driver. Its quiescent current remains relatively flat versus switching frequency. Whereas the RS-422 voltage mode driver increases exponentially in most case between 20 MHz-50 MHz. This is due to the overlap current that flows between the rails of the device when the internal gates switch. Whereas the current mode driver switches a fixed current between its output without any substantial overlap current. This is similar to some ECL and PECL devices, but without the heavy static I_{CC} requirements of the ECL/PECL designs. LVDS requires 80% less current than similar PECL devices. AC specifications for the driver are a tenfold improvement over other existing RS-422 drivers.

The TRI-STATE function allows the driver outputs to be disabled, thus obtaining an even lower power state when the transmission of data is not required.



Pin Descriptions

Pin No. (SOIC)	Name	Description
1, 7, 9, 15	D _{IN}	Driver input pin, TTL/CMOS compatible
2, 6, 10, 14	D _{OUT+}	Non-inverting driver output pin, LVDS levels
3, 5, 11, 13	D _{OUT-}	Inverting driver output pin, LVDS levels
4	EN	Active high enable pin, OR-ed with EN*
12	EN*	Active low enable pin, OR-ed with EN

Pin No. (SOIC)	Name	Description
16	V _{cc}	Power supply pin, +5V ± 10%
8	GND	Ground pin

Ordering Information

Operating	Package Type/	Order Number
Temperature	Number	
-40°C to +85°C	SOP/M16A	DS90C031TM
–55°C to +125°C	LCC/E20A	DS90C031E-QML
DS90C031E-QML	(NSID)	
5962-95833	(SMD)	

Note 1: "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. They are not meant to imply that the devices should be operated at these limits. The table of "Electrical Characteristics" specifies conditions of device operation.

Note 2: Current into device pins is defined as positive. Current out of device pins is defined as negative. All voltages are referenced to ground except: V_{OD1} and ΔV_{OD1} .

Note 3: All typicals are given for: V_{CC} = +5.0V, T_A = +25 $^\circ\text{C}.$

Note 4: Channel-to-Channel Skew is defined as the difference between the propagation delay of the channel and the other channels in the same chip with an event on the inputs.

Note 5: Chip to Chip Skew is defined as the difference between the minimum and maximum specified differential propagation delays.

Note 6: Generator waveform for all tests unless otherwise specified: f = 1 MHz, Z_0 = 50 Ω , $t_r \le 6$ ns, and $t_f \le 6$ ns.

Note 7: ESD Ratings:

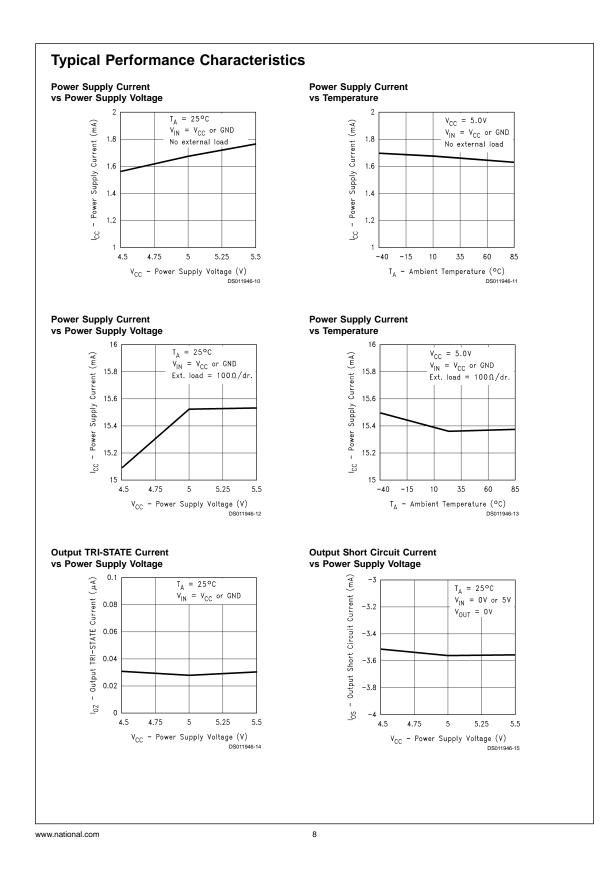
HBM (1.5 kΩ, 100 pF) ≥ 3,500V

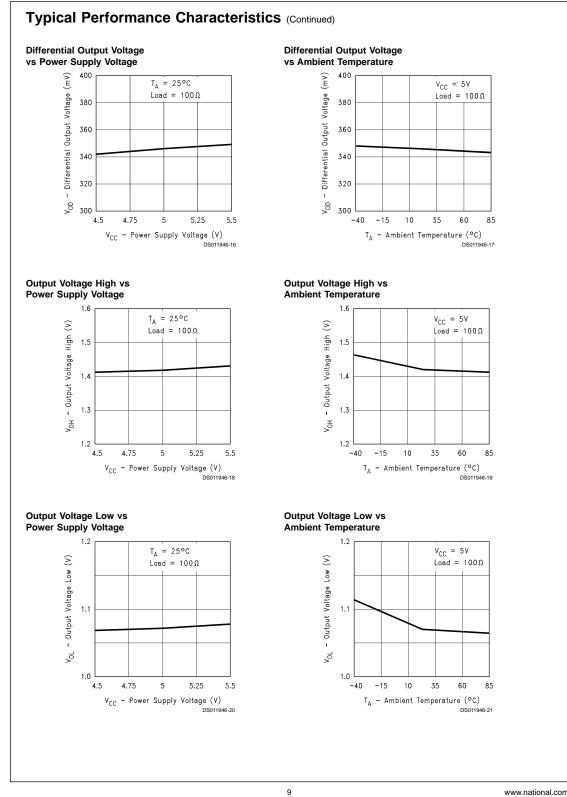
EIAJ (0 Ω , 200 pF) \ge 250V

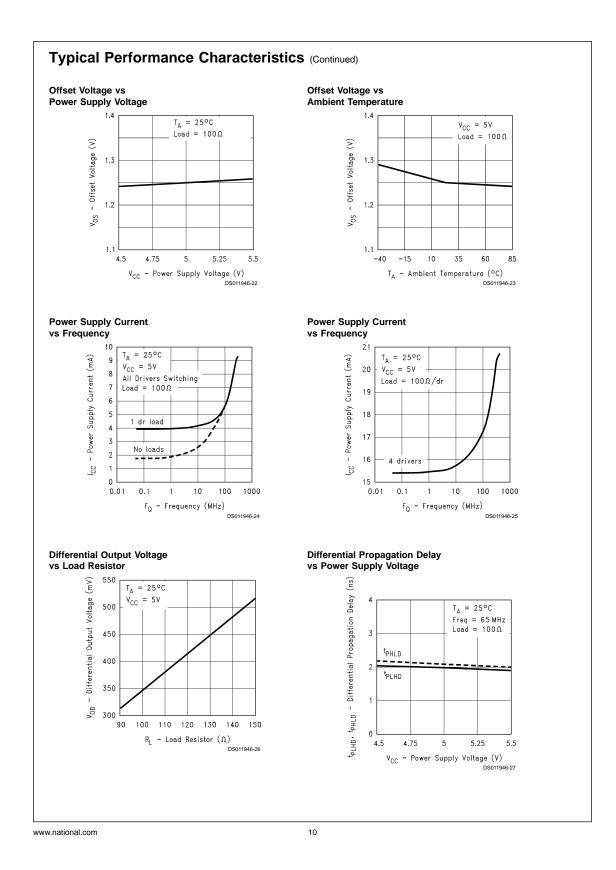
Note 8: Output short circuit current (I_{OS}) is specified as magnitude only, minus sign indicates direction only.

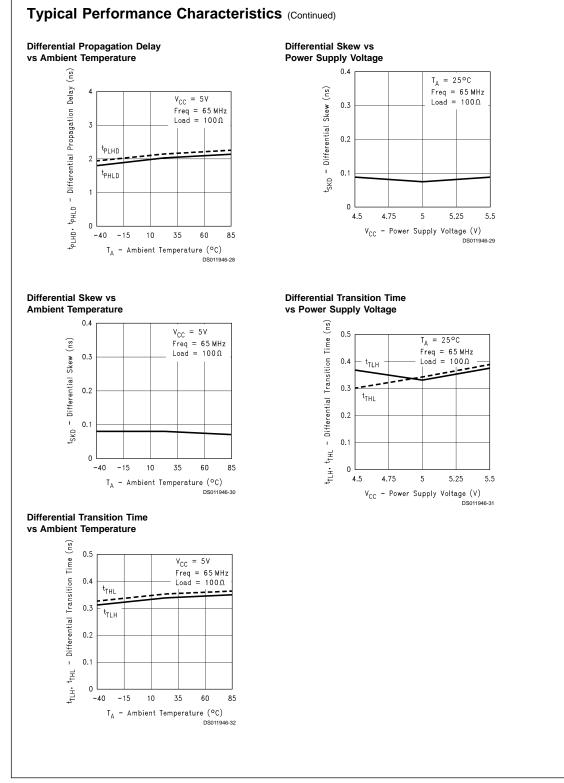
Note 9: CL includes probe and jig capacitance.

Note 10: Guaranteed by characterization data (DS90C031E).



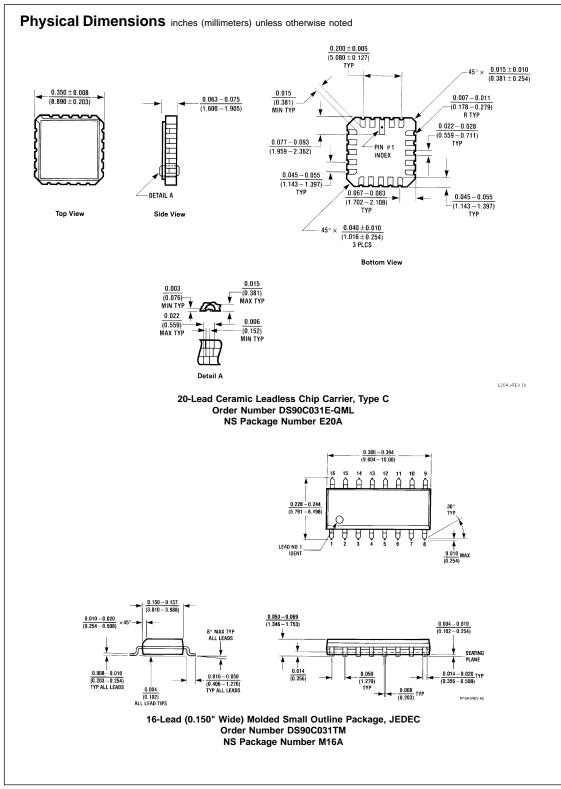






11

Downloaded from Elcodis.com electronic components distributor



LIFE SUPPORT POLICY

NATIONAL'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DE-VICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF NATIONAL SEMI-CONDUCTOR CORPORATION. As used herein:

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
- A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

National Semiconductor	National Semiconductor	National Semiconductor	National Semiconducto
Corporation	Europe	Asia Pacific Customer	Japan Ltd.
Americas	Fax: +49 (0) 1 80-530 85 86	Response Group	Tel: 81-3-5620-6175
Tel: 1-800-272-9959	Email: europe.support@nsc.com	Tel: 65-2544466	Fax: 81-3-5620-6179
Fax: 1-800-737-7018	Deutsch Tel: +49 (0) 1 80-530 85 85	Fax: 65-2504466	
Email: support@nsc.com	English Tel: +49 (0) 1 80-532 78 32	Email: sea.support@nsc.com	
	Français Tel: +49 (0) 1 80-532 93 58		
w.national.com	Italiano Tel: +49 (0) 1 80-534 16 80		

National does not assume any responsibility for use of any circuitry described, no circuit patent licenses are implied and National reserves the right at any time without notice to change said circuitry and specifications.